

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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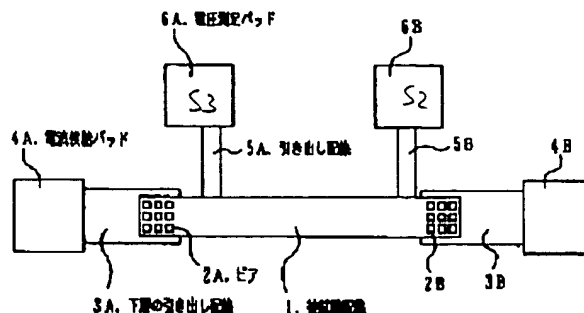
APPLICATION DATE : 08-12-98  
APPLICATION NUMBER : 10348216

APPLICANT : NEC CORP;

INVENTOR : SAITO YUMI;

INT.CL. : H01L 21/66

TITLE : SEMICONDUCTOR RELIABILITY  
EVALUATION DEVICE AND METHOD



- S1 failed!  
- zu testen der Bereich enthält  
keine Via!

ABSTRACT : PROBLEM TO BE SOLVED: To provide a semiconductor reliability evaluation device for accurately evaluating electromigration by eliminating a measurement error due to increase in resistance or the like caused by the loss of Al from the wiring end of wiring to be tested due to the drifting of Al.

SOLUTION: A device is configured to evaluate the electromigration of wiring to be tested using a pad for applying a constant current and a pad for measuring a voltage. In this case, via holes 2A and 2B where a material that differs from the material of wiring 1 to be tested and of pads 4A and 4B for applying a constant current is buried are provided, and pads 6A and 6B for measuring voltage are provided while being pinched by the via holes 2A and 2B and are provided on the same layer as the wiring 1 to be tested.

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